TEXAS INSTRUMENTS

SN74AHC32, SN54AHC32
SCLS247L – OCTOBER 1995 – REVISED FEBRUARY 2024

SNx4AHC32 Quadruple 2-Input Positive-OR Gates

1 Features

- Operating range 2V to 5.5V V_{CC}
- Low power consumption, 10µA maximum I_{CC}
- ±8mA output drive at 5V
- Latch-up performance exceeds 250mA per JESD 17

2 Applications

- Enable or disable a digital signal
- Controlling an indicator LED
- Translation between communication modules and system controllers

3 Description

The SNx4AHC32 devices are quadruple 2-input positive-OR gates. These devices perform the Boolean function $Y = \overline{A \times B}$ or $Y = A + B$ in positive logic.

Device Information

PART NUMBER	RATING	PACKAGE[1]
SN54AHC32	Military	FK (LCCC, 20)
		J (CDIP, 14)
		W (CFP, 14)
SN74AHC32	Commercial	DB (SSOP, 14)
		DGV (TVSOP, 14)
		D (SOIC, 14)
		N (PDIP, 14)
		NS (SO, 14)
		PW (TSSOP, 14)
		RGY (VQFN, 14)
		BQA (WQFN, 14)

(1) For all available packages, see the orderable addendum at the end of the data sheet.

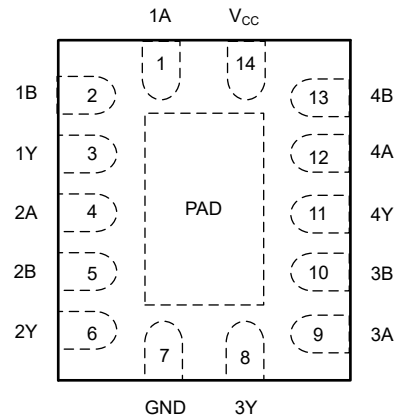A
B
Y

Logic Diagram (Positive Logic)

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Product Folder Links: *SN74AHC32 SN54AHC32*

4 Pin Configuration and Functions

**Figure 4-1. SN54AHC32 J or W
SN74AHC32 D, DB, DGV, N, NS or PW Package,
14-Pin (Top View)**

Figure 4-2. SN74AHC32 RGY or BQA Package, 14-Pin (Top View)
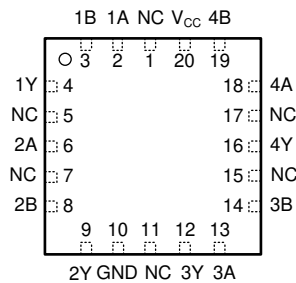
Figure 4-3. SN54AHC32 FK Package, 20-Pin (Top View)

Table 4-1. Pin Functions

PIN				TYPE[1]	DESCRIPTION
	SN74AHC32	SN54AHC32			
NAME	D, DB, DGV, N, NS, PW, RGY, BQA	J, W	FK		
1A	1	1	2	I	1A Input
1B	2	23	3	I	1B Input
1Y	3	3	4	O	1Y Output
2A	4	4	6	I	2A Input
2B	5	5	8	I	2B Input
2Y	6	6	9	O	2Y Output
3A	9	9	13	I	3A Input
3B	10	10	14	I	3B Input
3Y	8	8	12	O	3Y Output
4A	12	12	18	I	4A Input
4B	13	13	19	I	4B Input
4Y	11	11	16	O	4Y Output
GND	7	7	10	—	Ground Pin
NC	—	—	1, 5, 7, 11, 15, 17	—	No Connection

Table 4-1. Pin Functions (continued)

PIN				TYPE[1]	DESCRIPTION
NAME	SN74AHC32	SN54AHC32			
	D, DB, DGV, N, NS, PW, RGY, BQA	J, W	FK		
V_{CC}	14	14	20	—	Power Pin
Thermal Pad[2]	–	–	–	–	Thermal Pad

(1)   Signal Types: I = Input, O = Output, I/O = Input or Output.
(2)   RGY and BQA Package Only

5 Specifications

5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)[1]

		MIN	MAX	UNIT
Supply voltage range, V_{CC}		−0.5	7	V
Input voltage range, V_I [2]		−0.5	7	V
Output voltage range, V_O [2]		−0.5	V_{CC} + 0.5	V
Input clamp current, I_{IK} (V_I < 0)			-20	mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{CC})			±20	mA
Continuous output current, I_O (V_O = 0 to V_{CC})			±25	mA
Continuous current through V_{CC} or GND			±50	mA
Storage temperature range, T_{stg}		−65	150	°C

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

5.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001[1]	±2000	V
		Charged device model (CDM), per ANSI/ESDA/JEDEC JS-002[2]	±1000	

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

5.3 Recommended Operating Conditions

			SN54AHC32		SN74AHC32		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		2	5.5	2	5.5	V
V_{IH}	High-level input voltage	V_{CC}= 2 V	1.5		1.5		V
		V_{CC}= 3V	2.1		2.1		
		V_{CC}= 5.5 V	3.85		3.85		
V_{IL}	Low-level Input voltage	V_{CC}= 2 V		0.5		0.5	V
		V_{CC}= 3 V		0.9		0.9	
		V_{CC}= 5.5 V		1.65		1.65	
V_I	Input voltage		0	5.5	0	5.5	V
V_O	Output voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current	V_{CC}= 2 V		−50		−50	mA
		V_{CC}= 3.3 V ± 0.3 V		−4		−4	
		V_{CC}= 5 V ± 0.5 V		−8		−8	
I_{OL}	Low-level output current	V_{CC}= 2 V		50		50	mA
		V_{CC}= 3.3 V ± 0.3 V		4		4	
		V_{CC}= 5 V ± 0.5 V		8		8	
Δt/Δv	Input Transition rise or fall rate	V_{CC}= 3.3 V ± 0.3 V		100		100	ns/V
		V_{CC}= 5 V ± 0.5 V		20		20	
T_A	Operating free-air temperature		−55	125	−40	125	°C

5.4 Thermal Information

THERMAL METRIC[1]		SNx4AHC32								UNIT
		D[2]	DB[2]	DGV[2]	N[2]	NS[2]	PW[2]	RGY[3]	BQA	
		14	14	14	14	14	14	14	14	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	124.6	96	127	80	76	147.7	47	88.3	°C/W

(1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC package thermal metrics* application report.
(2) The package thermal impedance is calculated in accordance with JESD 51-7.
(3) The package thermal impedance is calculated in accordance with JESD 51-5

5.5 Electrical Characteristics

over operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	T_A = 25°C			T_A = –55°C TO 125°C		T_A = –40°C TO 85°C		T_A = –40°C TO 125°C		UNIT
						SN54AHC32		SN74AHC32		Recommended SN74AHC32		
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
V_{OH}	I_{OH} = –50 µA	2 V	1.9	2		1.9		1.9		1.9		V
		3 V	2.9	3		2.9		2.9		2.9		
		4.5 V	4.4	4.5		4.4		4.4		4.4		
	I_{OH} = –4 mA	3 V	2.58			2.48		2.48		2.48		
	I_{OH} = –8 mA	4.5 V	3.94			3.8		3.8		3.8		
V_{OL}	I_{OL} = 50 µA	2 V			0.1		0.1		0.1		0.1	V
		3 V			0.1		0.1		0.1		0.1	
		4.5 V			0.1		0.1		0.1		0.1	
	I_{OH} = 4 mA	3 V			0.36		0.5		0.44		0.5	
	I_{OH} = 8 mA	4.5 V			0.36		0.5		0.44		0.5	
I_I	V_I = 5.5 V or GND	0 V to 5.5 V			±0.1		±1[1]		±1		±1	µA
I_{CC}	V_I = V_{CC} or GND, I_O = 0	5.5 V			2		20		20		20	µA
C_i	V_I = V_{CC} or GND	5 V		2	10				10			pF

(1) On products compliant to MIL-PRF-38535, this parameter is not production tested at V_{CC} = 0 V.

5.6 Switching Characteristics, V_{CC} = 3.3 V ± 0.3 V

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 6-1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T_A = 25°C		T_A = –55°C TO 125°C		T_A = –40°C TO 85°C		T_A = –40°C TO 125°C		UNIT
						SN54AHC32		SN74AHC32		Recommended SN74AHC32		
				TYP	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A or B	Y	C_L = 15 pF	5.5[1]	7.9[1]	1[1]	9.5[1]	1	9.5	1	9.5	ns
t_{PHL}				5.5[1]	7.9[1]	1[1]	9.5[1]	1	9.5	1	9.5	
t_{PLH}	A or B	Y	C_L = 50 pF	8	11.4	1	13	1	13	1	13	ns
t_{PHL}				8	11.4	1	13	1	13	1	13	

(1) On products compliant to MIL-PRF-38535, this parameter is not production tested.

Product Folder Links: *SN74AHC32 SN54AHC32*

5.7 Switching Characteristics, V_{CC} = 5 V ± 0.5 V

over recommended operating free-air temperature range(unless otherwise noted) (see Figure 6-1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T_A = 25°C		T_A = –55°C TO 125°C		T_A = –40°C TO 85°C		T_A = –40°C TO 125°C		UNIT
										Recommended		
						SN54AHC32		SN74AHC32		SN74AHC32		
				TYP	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A or B	Y	C_L = 15 pF	3.8[1]	5.5[1]	1[1]	6.5[1]	1	6.5	1	6.5	ns
t_{PHL}				3.8[1]	5.5[1]	1[1]	6.5[1]	1	6.5	1	6.5	
t_{PLH}	A or B	Y	C_L = 50 pF	5.3	7.5	1	8.5	1	8.5	1	8.5	ns
t_{PHL}				5.3	7.5	1	8.5	1	8.5	1	8.5	

5.8 Noise Characteristics

V_{CC} = 5 V, C_L = 50 pF, T_A = 25°C[1]

| PARAMETER		SN74AHC32			UNIT
		MIN	TYP	MAX	
$V_{OL(P)}$	Quiet output, maximum dynamic V_{OL}		0.3	0.8	V
$V_{OL(V)}$	Quiet output, minimum dynamic V_{OL}		–0.3	–0.8	V
$V_{OH(V)}$	Quiet output, minimum dynamic V_{OH}		4.7		V
$V_{IH(D)}$	High-level dynamic input voltage	3.5			V
$V_{IL(D)}$	Low-level dynamic input voltage			1.5	V

(1)   Characteristics are for surface-mount packages only.

5.9 Operating Characteristics

V_{CC} = 5 V, T_A = 25°C

PARAMETER		TEST CONDITIONS		TYP	UNIT
C_{pd}	Power dissipation capacitance	No load,	f = 1 MHz	14	pF

Product Folder Links: SN74AHC32 SN54AHC32

6 Parameter Measurement Information
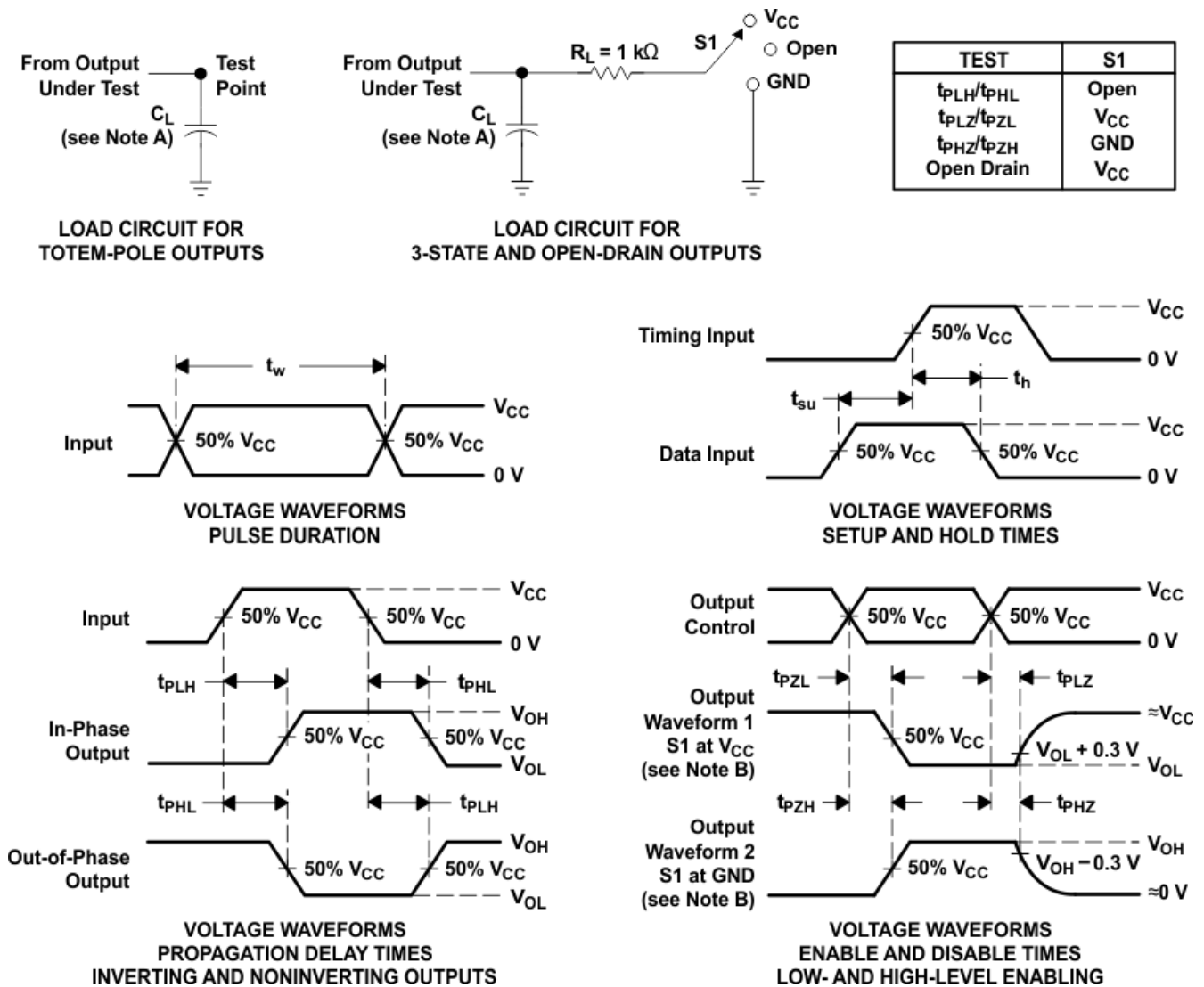
A. C_L includes probe and jig capacitance.

B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control.

Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.

C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, t_r ≤ 3 ns, t_f ≤ 3 ns.

D. The outputs are measured one at a time with one input transition per measurement.

E. All parameters and waveforms are not applicable to all devices.
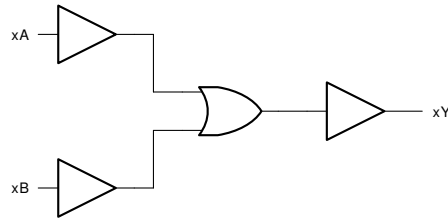
Figure 6-1. Load Circuit and Voltage Waveforms

7 Detailed Description

7.1 Overview

The SNx4AHC32 contains four independent 2-input OR Gates. Each gate performs the Boolean function Y = A + B in positive logic.

7.2 Functional Block Diagram

7.3 Feature Description

Product Folder Links: *SN74AHC32 SN54AHC32*

7.3.1 Standard CMOS Inputs

This device includes standard CMOS inputs. Standard CMOS inputs are high impedance and are typically modeled as a resistor in parallel with the input capacitance given in the *Electrical Characteristics*. The worst case resistance is calculated with the maximum input voltage, given in the *Absolute Maximum Ratings*, and the maximum input leakage current, given in the *Electrical Characteristics*, using Ohm's law (R = V ÷ I).

Standard CMOS inputs require that input signals transition between valid logic states quickly, as defined by the input transition time or rate in the *Recommended Operating Conditions* table. Failing to meet this specification will result in excessive power consumption and could cause oscillations. More details can be found in *Implications of Slow or Floating CMOS Inputs*.

Do not leave standard CMOS inputs floating at any time during operation. Unused inputs must be terminated at V_{CC} or GND. If a system will not be actively driving an input at all times, then a pull-up or pull-down resistor can be added to provide a valid input voltage during these times. The resistor value will depend on multiple factors; a 10kΩ resistor, however, is recommended and will typically meet all requirements.

7.3.2 Balanced CMOS Push-Pull Outputs

This device includes balanced CMOS push-pull outputs. The term *balanced* indicates that the device can sink and source similar currents. The drive capability of this device may create fast edges into light loads, so routing and load conditions should be considered to prevent ringing. Additionally, the outputs of this device are capable of driving larger currents than the device can sustain without being damaged. It is important to limit the output power of the device to avoid damage due to overcurrent. The electrical and thermal limits defined in the *Absolute Maximum Ratings* must be followed at all times.

Unused push-pull CMOS outputs should be left disconnected.

7.3.3 Clamp Diode Structure

The outputs to this device have both positive and negative clamping diodes, and the inputs to this device have negative clamping diodes only as shown in Figure 7-1.

CAUTION
Voltages beyond the values specified in the *Absolute Maximum Ratings* table can cause damage to the device. The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
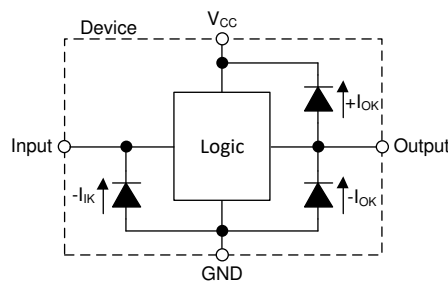
Figure 7-1. Electrical Placement of Clamping Diodes for Each Input and Output

7.4 Device Functional Modes

Table 7-1 lists the functional modes of the SNx4AHC32.

Table 7-1. Function Table

INPUTS[1]		OUTPUT Y
A	**B**	
H	H	H
L	H	H

Table 7-1. Function Table (continued)

| INPUTS[1] | | OUTPUT |
A	B	Y
H	L	H
L	L	L

(1) H = high voltage level, L = low voltage level, X = do not care, Z = high impedance

8 Application and Implementation

> **Note**
>
> Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

8.1 Application Information

In this application, three 2-input OR gates are combined to produce a 4-input OR gate function as shown in Figure 8-1. The fourth gate can be used for another application in the system, or the inputs can be grounded and the channel left unused.

The SNx4AHC32 is used to directly control the Enable pin of a fan driver. The fan driver requires only one input signal to be HIGH before being enabled, and should be disabled in the event that all signals go LOW. The 4-input OR gate function combines the four individual overheat signals into a single active-high enable signal.

Temperature sensors can often be spread throughout a system rather than being in a centralized location. This would mean longer length traces or wires to pass signals through leading to slower edge transitions. This makes the SNx4AHC32 useful for combining the incoming signals.

8.2 Typical Application
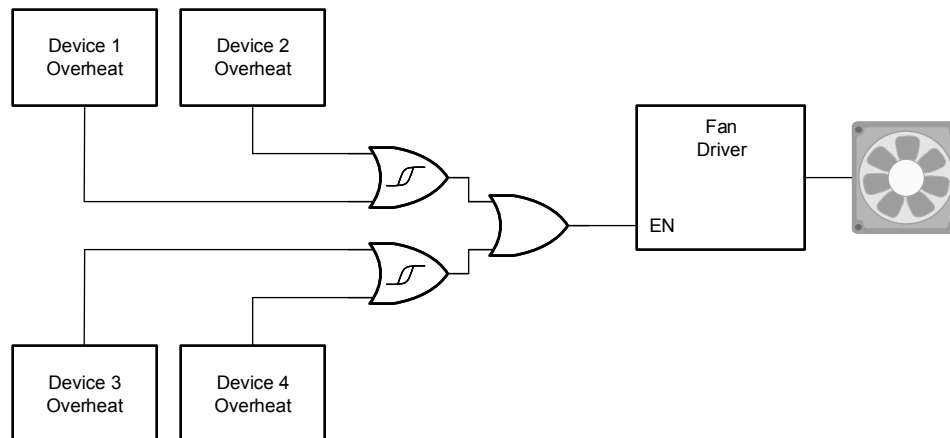
Figure 8-1. Typical Application Block Diagram

8.2.1 Design Requirements

8.2.1.1 Power Considerations

Ensure the desired supply voltage is within the range specified in the *Recommended Operating Conditions*. The supply voltage sets the electrical characteristics of the device as described in the *Electrical Characteristics* section.

The positive voltage supply must be capable of sourcing current equal to the maximum static supply current, I_{CC}, listed in the *Electrical Characteristics*, and any transient current required for switching.

The ground must be capable of sinking current equal to the total current to be sunk by all outputs of the SNx4AHC32 plus the maximum supply current, I_{CC}, listed in the *Electrical Characteristics*, and any transient current required for switching. The logic device can only sink as much current that can be sunk into its ground connection. Be sure to not exceed the maximum total current through GND listed in the *Absolute Maximum Ratings*.

The SNx4AHC32 can drive a load with a total capacitance less than or equal to 50 pF while still meeting all of the data sheet specifications. Larger capacitive loads can be applied; however, it is not recommended to exceed 50 pF.

The SNx4AHC32 can drive a load with total resistance described by $R_L \geq V_O / I_O$, with the output voltage and current defined in the *Electrical Characteristics* table with V_{OL}. When outputting in the HIGH state, the output voltage in the equation is defined as the difference between the measured output voltage and the supply voltage at the V_{CC} pin.

Total power consumption can be calculated using the information provided in *CMOS Power Consumption and Cpd Calculation* application note.

Thermal increase can be calculated using the information provided in *Thermal Characteristics of Standard Linear and Logic (SLL) Packages and Devices* application note.

> **CAUTION**
> The maximum junction temperature, $T_{J(max)}$ listed in the *Absolute Maximum Ratings*, is an additional limitation to prevent damage to the device. Do not violate any values listed in the *Absolute Maximum Ratings*. These limits are provided to prevent damage to the device.

8.2.1.2 Input Considerations

Input signals must cross to be considered a logic LOW, and to be considered a logic HIGH. Do not exceed the maximum input voltage range found in the *Absolute Maximum Ratings*.

Unused inputs must be terminated to either V_{CC} or ground. The unused inputs can be directly terminated if the input is completely unused, or they can be connected with a pull-up or pull-down resistor if the input will be used sometimes, but not always. A pull-up resistor is used for a default state of HIGH, and a pull-down resistor is used for a default state of LOW. The drive current of the controller, leakage current into the SNx4AHC32 (as specified in the *Electrical Characteristics*), and the desired input transition rate limits the resistor size. A 10-kΩ resistor value is often used due to these factors.

Refer to the *Feature Description* section for additional information regarding the inputs for this device.

8.2.1.3 Output Considerations

The ground voltage is used to produce the output LOW voltage. Sinking current into the output will increase the output voltage as specified by the V_{OL} specification in the *Electrical Characteristics*.

Unused outputs can be left floating. Do not connect outputs directly to V_{CC} or ground.

Refer to the *Feature Description* section for additional information regarding the outputs for this device.

8.2.2 Detailed Design Procedure

1. Add a decoupling capacitor from V_{CC} to GND. The capacitor needs to be placed physically close to the device and electrically close to both the V_{CC} and GND pins. An example layout is shown in the *Layout* section.
2. Ensure the capacitive load at the output is ≤ 50pF. This is not a hard limit; by design, however, it will optimize performance. This can be accomplished by providing short, appropriately sized traces from the SNx4AHC32 to one or more of the receiving devices.
3. Ensure the resistive load at the output is larger than (V_{CC} / $I_{O(max)}$)Ω. Doing this will prevent the maximum output current from the *Absolute Maximum Ratings* from being violated. Most CMOS inputs have a resistive load measured in MΩ; much larger than the minimum calculated previously.

4. Thermal issues are rarely a concern for logic gates; the power consumption and thermal increase, however, can be calculated using the steps provided in the application report, *CMOS Power Consumption and Cpd Calculation*.

8.2.3 Application Curves
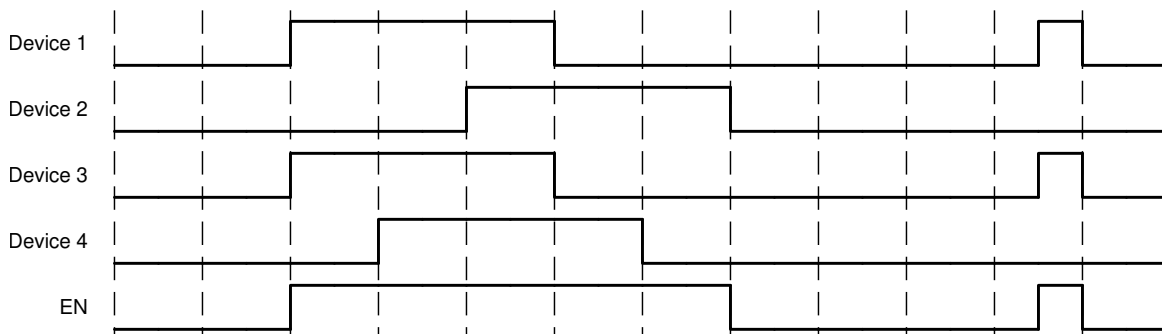
Figure 8-2. Application Timing Diagram

8.3 Power Supply Recommendations

The power supply can be any voltage between the minimum and maximum supply voltage rating located in the *Recommended Operating Conditions*. Each V_{CC} terminal should have a good bypass capacitor to prevent power disturbance. A 0.1-µF capacitor is recommended for this device. It is acceptable to parallel multiple bypass capacitors to reject different frequencies of noise. The 0.1-µF and 1-µF capacitors are commonly used in parallel. The bypass capacitor should be installed as close to the power terminal as possible for best results, as shown in the following layout example.

8.4 Layout

8.4.1 Layout Guidelines

When using multiple-input and multiple-channel logic devices, inputs must never be left floating. In many cases, functions or parts of functions of digital logic devices are unused (for example, when only two inputs of a triple-input AND gate are used or only 3 of the 4 buffer gates are used). Such unused input pins must not be left unconnected because the undefined voltages at the outside connections result in undefined operational states. All unused inputs of digital logic devices must be connected to a logic high or logic low voltage, as defined by the input voltage specifications, to prevent them from floating. The logic level that must be applied to any particular unused input depends on the function of the device. Generally, the inputs are tied to GND or V_{CC}, whichever makes more sense for the logic function or is more convenient.

8.4.2 Layout Example
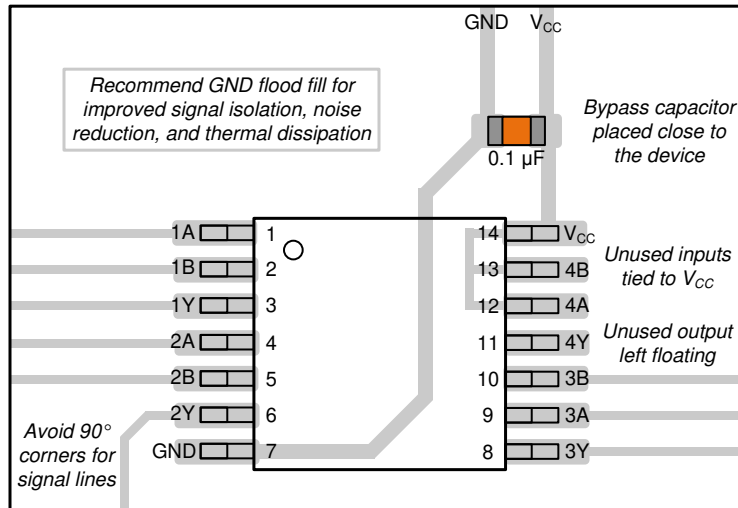
Figure 8-3. Example Layout for the SNx4AHC32

9 Device and Documentation Support

TI offers an extensive line of development tools. Tools and software to evaluate the performance of the device, generate code, and develop solutions are listed below.

9.1 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. Click on *Notifications* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

9.2 Support Resources

TI E2E™ support forums are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Use.

9.3 Trademarks

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9.4 Electrostatic Discharge Caution

This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

9.5 Glossary

TI Glossary   This glossary lists and explains terms, acronyms, and definitions.

10 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision K (October 2023) to Revision L (February 2024)	**Page**
• Updated RθJA value: D = 86 to 124.6, all values in °C/W 6	

Changes from Revision J (May 2023) to Revision K (October 2023)	**Page**
• Updated RθJA values: PW = 113 to 147.7, all values in °C/W 6	

11 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9682501Q2A	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9682501Q2A SNJ54AHC 32FK	Samples
5962-9682501QCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9682501QCA SNJ54AHC32J	Samples
5962-9682501QDA	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9682501QDA SNJ54AHC32W	Samples
SN74AHC32BQAR	ACTIVE	WQFN	BQA	14	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	AHC32	Samples
SN74AHC32DBR	ACTIVE	SSOP	DB	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HA32	Samples
SN74AHC32DGVR	ACTIVE	TVSOP	DGV	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HA32	Samples
SN74AHC32DR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	AHC32	Samples
SN74AHC32N	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-40 to 125	SN74AHC32N	Samples
SN74AHC32NSR	ACTIVE	SO	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	AHC32	Samples
SN74AHC32PWR	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HA32	Samples
SN74AHC32RGYR	ACTIVE	VQFN	RGY	14	3000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	HA32	Samples
SNJ54AHC32FK	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9682501Q2A SNJ54AHC 32FK	Samples
SNJ54AHC32J	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9682501QCA SNJ54AHC32J	Samples
SNJ54AHC32W	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9682501QDA SNJ54AHC32W	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN54AHC32, SN74AHC32 :

● Catalog : SN74AHC32

● Enhanced Product : SN74AHC32-EP, SN74AHC32-EP

● Military : SN54AHC32

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product

- Enhanced Product - Supports Defense, Aerospace and Medical Applications

- Military - QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

TAPE AND REEL INFORMATION

REEL DIMENSIONS

TAPE DIMENSIONS

A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AHC32BQAR	WQFN	BQA	14	3000	180.0	12.4	2.8	3.3	1.1	4.0	12.0	Q1
SN74AHC32DBR	SSOP	DB	14	2000	330.0	16.4	8.35	6.6	2.4	12.0	16.0	Q1
SN74AHC32DGVR	TVSOP	DGV	14	2000	330.0	12.4	6.8	4.0	1.6	8.0	12.0	Q1
SN74AHC32DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74AHC32NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74AHC32PWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74AHC32RGYR	VQFN	RGY	14	3000	330.0	12.4	3.75	3.75	1.15	8.0	12.0	Q1

PACKAGE MATERIALS INFORMATION

TAPE AND REEL BOX DIMENSIONS

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AHC32BQAR	WQFN	BQA	14	3000	210.0	185.0	35.0
SN74AHC32DBR	SSOP	DB	14	2000	356.0	356.0	35.0
SN74AHC32DGVR	TVSOP	DGV	14	2000	356.0	356.0	35.0
SN74AHC32DR	SOIC	D	14	2500	356.0	356.0	35.0
SN74AHC32NSR	SO	NS	14	2000	356.0	356.0	35.0
SN74AHC32PWR	TSSOP	PW	14	2000	356.0	356.0	35.0
SN74AHC32RGYR	VQFN	RGY	14	3000	356.0	356.0	35.0

TUBE

T - Tube height

L - Tube length

W - Tube width

B - Alignment groove width

*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
5962-9682501Q2A	FK	LCCC	20	55	506.98	12.06	2030	NA
5962-9682501QDA	W	CFP	14	25	506.98	26.16	6220	NA
SN74AHC32N	N	PDIP	14	25	506	13.97	11230	4.32
SN74AHC32N	N	PDIP	14	25	506	13.97	11230	4.32
SNJ54AHC32FK	FK	LCCC	20	55	506.98	12.06	2030	NA
SNJ54AHC32W	W	CFP	14	25	506.98	26.16	6220	NA

FK 20

LCCC - 2.03 mm max height

8.89 x 8.89, 1.27 mm pitch

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

4229370VA\

Images above are just a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

4040083-5/G

TEXAS
INSTRUMENTS

PIN 1 ID
(OPTIONAL)

1

12X .100
[2.54]

14

.754-.785
[19.15-19.94]

7

8

B

.245-.283
[6.22-7.19]

4X .005 MIN
[0.13]

.015-.060 TYP
[0.38-1.52]

14X .045-.065
[1.15-1.65]

14X .014-.026
[0.36-0.66]

⊕ .010 [0.25] C A B

.2 MAX TYP
[5.08]

.13 MIN TYP
[3.3]

C

SEATING PLANE

.308-.314
[7.83-7.97]
AT GAGE PLANE

.015
[0.38]

GAGE PLANE

0°-15°
TYP

14X .008-.014
[0.2-0.36]

4214771/A   05/2017

NOTES:

1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This package is hermitically sealed with a ceramic lid using glass frit.
4. Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
5. Falls within MIL-STD-1835 and GDIP1-T14.

SEE DETAIL A

(.300) TYP
[7.62]

SEE DETAIL B

1

14

12X (.100)
[2.54]

SYMM
₵

14X (∅ .039)
[1]

7

8

SYMM
₵

LAND PATTERN EXAMPLE
NON-SOLDER MASK DEFINED
SCALE: 5X

.002 MAX
[0.05]
ALL AROUND

(.063)
[1.6]

SOLDER MASK
OPENING

METAL

(R.002) TYP
[0.05]

DETAIL A
SCALE: 15X

METAL

(∅ .063)
[1.6]

SOLDER MASK
OPENING

.002 MAX
[0.05]
ALL AROUND

DETAIL B
13X, SCALE: 15X

4214771/A   05/2017

D (R−PDSO−G14)   PLASTIC SMALL OUTLINE

NOTES: A. All linear dimensions are in inches (millimeters).
         B. This drawing is subject to change without notice.
         C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall
             not exceed 0.006 (0,15) each side.
         D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
         E. Reference JEDEC MS−012 variation AB.

D (R−PDSO−G14)   PLASTIC SMALL OUTLINE

Example Board Layout
(Note C)

Stencil Openings
(Note D)

12x1,27

14x0,55

12x1,27

14x1,50

5,40

5,40

Example
Non Soldermask Defined Pad

Example
Pad Geometry
(See Note C)

0,60

1,55

Example
Solder Mask Opening
(See Note E)

0.07
All Around

4211283−3/E 08/12

NOTES: A. All linear dimensions are in millimeters.
         B. This drawing is subject to change without notice.
         C. Publication IPC−7351 is recommended for alternate designs.
         D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should
             contact their board assembly site for stencil design recommendations. Refer to IPC−7525 for other stencil recommendations.
         E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

PW (R−PDSO−G14)   PLASTIC SMALL OUTLINE

0,65

0,30
0,19

⊕ | 0,10 Ⓜ

14

8

D⟋ 4,50
4,30

6,60
6,20

1

7

5,10
4,90

C⟋

0,15 NOM

Gage Plane

0°−8°

0,25

0,75
0,50

1,20 MAX

0,15
0,05

Seating Plane

⌒ | 0,10

4040064−3/G 02/11

NOTES: A.   All linear dimensions are in millimeters.   Dimensioning and tolerancing per ASME Y14.5M−1994.
         B.   This drawing is subject to change without notice.
         C⟋   Body length does not include mold flash, protrusions, or gate burrs.   Mold flash, protrusions, or gate burrs shall
              not exceed 0,15 each side.
         D⟋   Body width does not include interlead flash.   Interlead flash shall not exceed 0,25 each side.
         E.   Falls within JEDEC MO−153

N (R–PDIP–T)**
16 PINS SHOWN

PLASTIC DUAL–IN–LINE PACKAGE

DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
⚠C MS–001 VARIATION	AA	BB	AC	AD

A

16   9

0.260 (6,60)
0.240 (6,10)

1   8

0.070 (1,78)
0.045 (1,14) ⚠D

0.045 (1,14)
0.030 (0,76) ⚠D

0.020 (0,51) MIN

0.200 (5,08) MAX

Seating Plane

0.125 (3,18) MIN

0.100 (2,54)

0.021 (0,53)
0.015 (0,38)

⊕ 0.010 (0,25) Ⓜ

14/18 Pin Only
20 Pin vendor option ⚠D

0.325 (8,26)
0.300 (7,62)

0.015 (0,38)

Gauge Plane

0.010 (0,25) NOM

0.430 (10,92) MAX

4040049/E   12/2002

NOTES: A.   All linear dimensions are in inches (millimeters).
         B.   This drawing is subject to change without notice.
      ⚠C   Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
      ⚠D   The 20 pin end lead shoulder width is a vendor option, either half or full width.

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DB (R-PDSO-G**)   **PLASTIC SMALL-OUTLINE**

28 PINS SHOWN

PINS ** DIM	14	16	20	24	28	30	38
A MAX	6,50	6,50	7,50	8,50	10,50	10,50	12,90
A MIN	5,90	5,90	6,90	7,90	9,90	9,90	12,30

4040065 /E 12/01

NOTES: A. All linear dimensions are in millimeters.
        B. This drawing is subject to change without notice.
        C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
        D. Falls within JEDEC MO-150

RGY (S-PVQFN-N14)   PLASTIC QUAD FLATPACK NO-LEAD

3,65
3,35

A

B

13   9

14   8

3,65
3,35

1   7

2   6

Pin 1 Index Area
Top and Bottom

F

1,00
0,80

0,20 Nominal
Lead Frame

Seating Plane

⌒ 0,08 C

0,05
0,00
Seating Height

C

2,00

0,50

14X 0,50
0,30

2   6

1   7

THERMAL PAD

SIZE AND SHAPE
SHOWN ON SEPRATE SHEET

1,50

14   8

14X 0,30
0,18

13   9

⊕ 0,10 Ⓜ C A B
0,05 Ⓜ C

Bottom View

4203539-2/I   06/2011

NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
          B. This drawing is subject to change without notice.
          C. QFN (Quad Flatpack No-Lead) package configuration.
          D. The package thermal pad must be soldered to the board for thermal and mechanical performance.
          E. See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
          F. Pin 1 identifiers are located on both top and bottom of the package and within the zone indicated.
              The Pin 1 identifiers are either a molded, marked, or metal feature.
          G. Package complies to JEDEC MO-241 variation BA.

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RGY (S–PVQFN–N14)   PLASTIC QUAD FLATPACK NO–LEAD

THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No–Lead (QFN) package and its advantages, refer to Application Report, QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271. This document is available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.

Bottom View

Exposed Thermal Pad Dimensions

4206353–2/P   03/14

NOTE: All linear dimensions are in millimeters

RGY (S-PVQFN-N14)   PLASTIC QUAD FLATPACK NO-LEAD

Example Board Layout

4,30

4,30

2,60

1,50

2,05

2,05

Note D

8x0,50

0.28

Example Stencil Design
0.125mm Stencil Thickness
(Note E)

4,25

4,25

2,65

1,50

0,82 SQ

0,50

0,80 x 14 PL.

8x0,50

0,23 x 14 PL.

64% solder coverage by printed
area on center thermal pad

Non Solder Mask
Defined Pad

Example
Solder Mask Opening
(Note F)

0,08

R0,14

0,85

0,07

0,28

All Around

Example
Pad Geometry
(Note C)

Example Via Layout Design
may vary depending on constraints
(Note D, F)

1,00

1,00

6xØ0,3

4208122-2/P   03/14

NOTES: A.   All linear dimensions are in millimeters.
         B.   This drawing is subject to change without notice.
         C.   Publication IPC-7351 is recommended for alternate designs.
         D.   This package is designed to be soldered to a thermal pad on the board. Refer to Application Note, Quad Flat-Pack
              QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271, and also the Product Data Sheets
              for specific thermal information, via requirements, and recommended board layout.
              These documents are available at www.ti.com <http://www.ti.com>.
         E.   Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should
              contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
         F.   Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads.

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BQA 14

2.5 x 3, 0.5 mm pitch

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

4227145/A

B

2.6
2.4

A

PIN 1 INDEX AREA

3.1
2.9

0.8
0.7

C

SEATING PLANE

0.08 C

0.05
0.00

1.1
0.9

2X 0.5

(0.2) TYP

7   8

8X 0.5

6   9

SYMM

2X
2

1.6
1.4

15

13

PIN 1 ID
(OPTIONAL)

2

14X 0.3
0.2

1   14

0.1 (M) C A B

0.05 (M) C

SYMM

14X 0.5
0.3

4224636/A   11/2018

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for optimal thermal and mechanical performance.

LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 20X

0.07 MAX
ALL AROUND

METAL

EXPOSED METAL

SOLDER MASK
OPENING

NON-SOLDER MASK
DEFINED
(PREFERRED)

0.07 MIN
ALL AROUND

METAL UNDER
SOLDER MASK

EXPOSED METAL

SOLDER MASK
OPENING

SOLDER MASK
DEFINED

4224636/A   11/2018

NOTES: (continued)

4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271) .

5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.
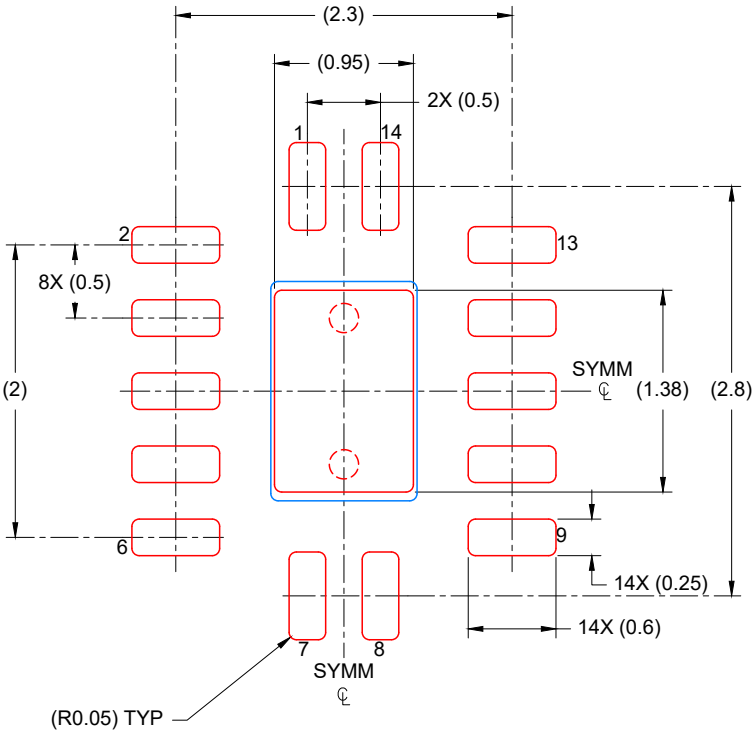
SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD
88% PRINTED COVERAGE BY AREA
SCALE: 20X

4224636/A   11/2018

NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

MECHANICAL DATA

14-PINS SHOWN

DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

NOTES: A.   All linear dimensions are in millimeters.
         B.   This drawing is subject to change without notice.
         C.   Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

W (R−GDFP−F14)   CERAMIC DUAL FLATPACK

Base and Seating Plane

$\dfrac{0.045\ (1,14)}{0.026\ (0,66)}$

$\dfrac{0.260\ (6,60)}{0.235\ (5,97)}$

$\dfrac{0.008\ (0,20)}{0.004\ (0,10)}$

$\dfrac{0.080\ (2,03)}{0.045\ (1,14)}$

0.280 (7,11) MAX

1   14

$\dfrac{0.019\ (0,48)}{0.015\ (0,38)}$

$\dfrac{0.390\ (9,91)}{0.335\ (8,51)}$

0.050 (1,27)

0.005 (0,13) MIN
4 Places

7   8

$\dfrac{0.360\ (9,14)}{0.250\ (6,35)}$ $\dfrac{0.360\ (9,14)}{0.250\ (6,35)}$

4040180−2/F   04/14

NOTES: A.   All linear dimensions are in inches (millimeters).
         B.   This drawing is subject to change without notice.
         C.   This package can be hermetically sealed with a ceramic lid using glass frit.
         D.   Index point is provided on cap for terminal identification only.
         E.   Falls within MIL STD 1835 GDFP1−F14

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